

Electronic Patent Application Fee Transmittal

Application Number:	10616097			
Filing Date:	08-Jul-2003			
Title of Invention:	Multiple-step electrodeposition process for direct copper plating on barrier metals			
First Named Inventor/Applicant Name:	Zhi-Wen Sun			
Filer:	Keith Patrick Taboada			
Attorney Docket Number:	AMAT/8241/CMP/ECP/RKK			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				130